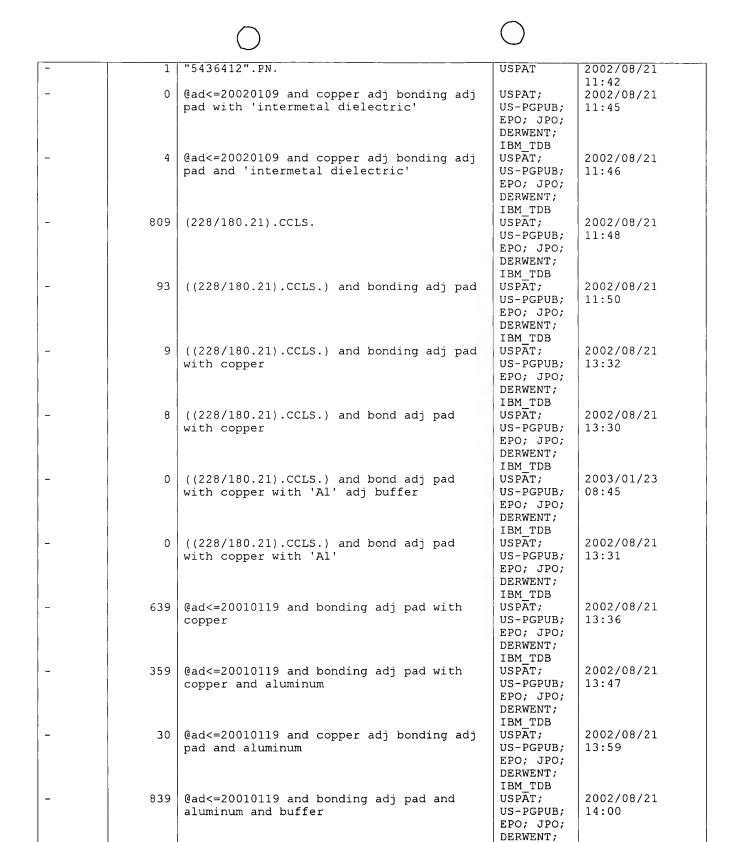


| L Number | Hits | Search Text | DB | Time stamp |
|-------------|------|--|--|------------------------------|
| 1 | 2356 | (438/612).ccls. or (438/597).ccls. and | USPAT; | 2003/08/05 |
| | | @ad<=20020109 | US-PGPUB; EPO; JPO; DERWENT; | 10:34 |
| 2 | 798 | (228/180.21).ccls. and @ad<=20020109 | IBM_TDB USPAT; US-PGPUB; EPO; JPO; | 2003/08/05 |
| 3 | 2531 | (438/613-617).ccls. and @ad<=20020109 | DERWENT; IBM_TDB USPAT; US-PGPUB; | 2003/08/05 10:38 |
| 4 | 586 | (257/459).ccls. and @ad<=20020109 | EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; | 2003/08/05 |
| 5 | 1320 | (257/784).ccls. and @ad<=20020109 | EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; | 2003/08/05 |
| 6 | 1288 | (257/786).ccls. and @ad<=20020109 | EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; | 2003/08/05 10:42 |
| 7 | 782 | (257/781-782).ccls. and @ad<=20020109 | EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; | 2003/08/05 |
| 8 | 1782 | (257/676).ccls. and @ad<=20020109 | DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; | 2003/08/05 |
| 11 / | 27 | @ad<=20020109 and 'bonding pad' near3 'Cu' with 'Al' | DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; | 2003/08/05 11:19 |
| 12 | 63 | @ad<=20020109 and 'bonding pad' near3 'Copper' with 'Aluminum' | DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; | 2003/08/05 11:32 |
| 13 | 34 | @ad<=20020109 and CVC.as. and interconnect | IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; | 2003/08/05 |
| 14 | 1 | ("6333559").PN. | IBM_TDB USPAT | 2003/08/05 |
| 15 | 4 | (("5785236") or ("6197613") or ("6162652") or ("6555759")).PN. | USPAT | 11:38 2003/08/05 11:40 |
| 18 | 0 | "20020164840" | USPAT | 2003/08/05 |
| 19 | 0 | "2002/0164840" | USPAT | 2003/08/05 |
| 20 | 2 | "20020164840" | USPAT; US-PGPUB; EPO; | 11:42 2003/08/05 11:42 |
| | | | DERWENT; IBM TDB | |

| 21 | 2 | "20010035452" | USPAT; | 2003/08/05 |
|----|------|--|------------------------|------------------|
| | | | US-PGPUB; EPO; | 11:43 |
| | | | DERWENT; | |
| | | | IBM TDB | |
| 22 | 2 | "20020047218" | USPAT; | 2003/08/05 |
| | | | US-PGPUB; | 11:43 |
| | | | EPO; | |
| | | | DERWENT; | |
| | 2054 | (438/612).ccls. or (438/597).ccls. and | IBM_TDB USPAT; | 2003/08/05 |
| | 2034 | @ad<=20020109 | US-PGPUB; | 10:33 |
| | | Caa (2002010) | EPO; JPO; | 10.55 |
| | | | DERWENT; | |
| | | | IBM_TDB | |
| - | 337 | ((438/612).ccls. or (438/597).ccls. and | USPAT; | 2002/08/21 |
| | | @ad<=20020109) and copper and aluminum | US-PGPUB; | 11:04 |
| | | | EPO; JPO; DERWENT; | |
| | | | IBM TDB | |
| - | 74 | ((438/612).ccls. or (438/597).ccls. and | USPAT; | 2003/01/23 |
| 1 | | @ad<=20020109) and 'bonding pad' with | US-PGPUB; | 10:01 |
| | | 'integrated circuit' | EPO; JPO; | |
| | | | DERWENT; | |
| _ | 1 | ((438/612).ccls. or (438/597).ccls. and | IBM_TDB USPAT; | 2002/08/21 |
| _ | | (4367612).0018. OF (4367597).0018. and @ad<=20020109) and Cu adj bonding adj pad | US-PGPUB; | 11:13 |
| | | with 'integrated circuit' | EPO; JPO; | -1.15 |
| | | | DERWENT; | |
| | | | IBM_TDB | |
| _ | 6 | ((438/612).ccls. or (438/597).ccls. and | USPAT; | 2002/08/21 |
| | | @ad<=20020109) and Copper adj bonding adj | US-PGPUB; | 11:14 |
| | | pad | EPO; JPO; DERWENT; | |
| | İ | | IBM TDB | |
| _ | 1143 | @ad<=20020109 and cu adj 'bonding pad' | USPAT; | 2002/08/21 |
| | | with 'IMD' or 'intermetal dielectric' | US-PGPUB; | 11:45 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| _ | 0 | @ad<=20020109 and cu adj 'bonding pad' | IBM_TDB USPAT; | 2002/08/21 |
| | | with 'IMD' | US-PGPUB; | 11:27 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM_TDB | 0000/65/55 |
| - | 0 | @ad<=20020109 and cu adj 'bonding pad' | USPĀT; | 2002/08/21 |
| | | with 'intermetal dielectric' | US-PGPUB; EPO; JPO; | 11:27 |
| | | | DERWENT; | |
| | | | IBM TDB | |
| - | 6 | @ad<=20020109 and cu adj 'bonding pad' | USPAT; | 2003/01/23 |
| | | with 'Al' | US-PGPUB; | 09:03 |
| | | | EPO; JPO; | |
| | | | DERWENT; IBM TDB | |
| _ | 3 | @ad<=20020109 and cu adj 'bonding pad' | USPAT; | 2002/08/21 |
| | | and 'IMD' | US-PGPUB; | 11:43 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | _ | #2042245# px | IBM_TDB | 2002/09/21 |
| - | 1 | "3942245".PN. | USPAT | 2002/08/21 |
| _ | 1 | "5075965".PN. | USPAT | 2002/08/21 |
| | | | | 11:40 |
| - | 1 | "5288006".PN. | USPAT | 2002/08/21 |
| | | | | 11:40 |
| - | 1 | "5376235".PN. | USPAT | 2002/08/21 |
| _ | 1 | "5384284".PN. | USPAT | 11:41 2002/08/21 |
| _ | | J304204 .FN. | USPAI | 11:41 |
| L | J | | l | ***** |



'bonding pad' and apparatus

IBM TDB

US-PGPUB; EPO; JPO; DERWENT; IBM TDB 2002/08/21 15:03

USPAT;

| _ | 3573 | ((257/459) or (257/676) or (257/786) or | USPAT; | 2002/08/21 |
|---|------|---|---|----------------|
| 1 | | (275/670) or (257/672)).CCLS. | US-PGPUB; | 15:07 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM_TDB | |
| - | 1779 | (438/612).ccls. and @ad<=20020109 | USPAT; | 2003/01/23 |
| | | | US-PGPUB; | 08:47 |
| | | | EPO; JPO; | |
| ! | | | DERWENT; | |
| | | | IBM_TDB | |
| - | 1 | bond adj pad with copper with 'Al' and | USPAT; | 2003/01/23 |
| | | 'buffer' | US-PGPUB; | 08:46 |
| | | | EPO; JPO; | |
| | | | DERWENT; | 7 |
| | | | IBM_TDB | |
| _ | 11 | 'bond' and 'pad' with copper with 'Al' | USPAT; | 2003/01/23 |
| | | and 'buffer' | US-PGPUB; | 08:54 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM_TDB | |
| - | 284 | (438/48).ccls. and @ad<=20020109 | USPAT; | 2003/01/23 |
| | | | US-PGPUB; | 08:47 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM_TDB | |
| - | 1722 | (438/614).ccls. and @ad<=20020109 | USPAT; | 2003/08/05 |
| | | | US-PGPUB; | 10:35 |
| 1 | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM_TDB | |
| - | 573 | (257/459).ccls. and @ad<=20020109 | USPAT; | 2003/08/05 |
| | | | US-PGPUB; | 10:35 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM_TDB | |
| - | 1222 | (257/784).ccls. and @ad<=20020109 | USPAT; | 2003/08/05 |
| | | | US-PGPUB; | 10:37 |
| | | | EPO; JPO; | |
| | | | DERWENT; | 1 |
| | | 1077/7061 | IBM_TDB | 2002/00/05 |
| - | 1209 | (257/786).ccls. and @ad<=20020109 | USPAT; | 2003/08/05 |
| | | | US-PGPUB; | 10:39 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | 1057 (704 700) | IBM_TDB | 2222 / 22 / 25 |
| - | 735 | (257/781-782).ccls. and @ad<=20020109 | USPAT; | 2003/08/05 |
| 1 | | | US-PGPUB; | 10:40 |
| | | | EPO; JPO; | |
| 1 | | | DERWENT; | |
| | 1200 | (257/774) gglg and Bad-20020100 | IBM_TDB USPAT; | 2003/01/23 |
| - | 1392 | (257/774).ccls. and @ad<=20020109 | USPAT; US-PGPUB; | 11:44 |
| | | | | 11.44 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | , | thond and twith teanment with this and | IBM_TDB USPAT; | 2003/01/23 |
| - | 1 | 'bond pad' with 'copper' with 'Al' and 'buffer' | US-PGPUB; | 08:55 |
| ! | | parier | EPO; JPO; | 00.33 |
| 1 | | | DERWENT; | |
| | | | IBM TDB | |
| _ | 1 | bonding pad' with 'copper' with 'Al' and | USPAT; | 2003/01/23 |
| | 1 | 'buffer' | US-PGPUB; | 08:56 |
| | | Darrer | EPO; JPO; | ***** |
| | | | DERWENT; | |
| | | | IBM TDB | |
| _ | 122 | 'bonding pad' with 'Cu' with 'Al' | USPAT; | 2003/01/23 |
| | 122 | Donathy pad with the with Ai | US-PGPUB; | 09:05 |
| | | | EPO; JPO; | |
| | 1 | | DERWENT; | |
| | | | IBM TDB | |
| L | | | 1 | L |





| - | 117 | @ad<=20020109 and 'bonding pad' with 'Cu' | USPAT; | 2003/01/23 |
|---|-----|---|-----------|------------|
| | | with 'Al' | US-PGPUB; | 09:01 |
| 1 | | | EPO; JPO; | |
|] | | | DERWENT; | |
| | | | IBM TDB | |
| | 6 | @ad<=20020109 and cu adj 'bonding pad' | USPAT; | 2003/01/23 |
|] | | with 'Al' | US-PGPUB; | 09:03 |
| 1 | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM TDB | |
| _ | 117 | @ad<=20020109 and 'bonding pad' with 'Cu' | USPAT; | 2003/08/05 |
| | | with 'Al' | US-PGPUB; | 11:18 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM TDB | |
| - | 1 | "4811081".PN. | USPĀT | 2003/01/23 |
| | _ | | | 09:57 |
| _ | 1 | "5001542".PN. | USPAT | 2003/01/23 |
| | | | | 09:57 |
| _ | 1 | "6108212".PN. | USPAT | 2003/01/23 |
| | | | | 09:57 |
| | 1 | "6064120".PN. | USPAT | 2003/01/23 |
| | | | | 09:58 |
| - | 246 | @ad<=20020109 and 'bonding pad' with | USPAT; | 2003/01/23 |
| | | 'integrated circuit' and 'Cu' and 'Al' | US-PGPUB; | 10:02 |
| | | - | EPO; JPO; | |
| | | | DERWENT; | |
|] | | | IBM TDB | |
| _ | 231 | (257/784).ccls. and @ad<=20020109 and | USPAT; | 2003/01/23 |
| | | 'Copper' and 'aluminum' | US-PGPUB; | 10:38 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM TDB | |